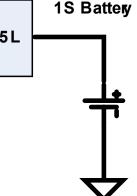
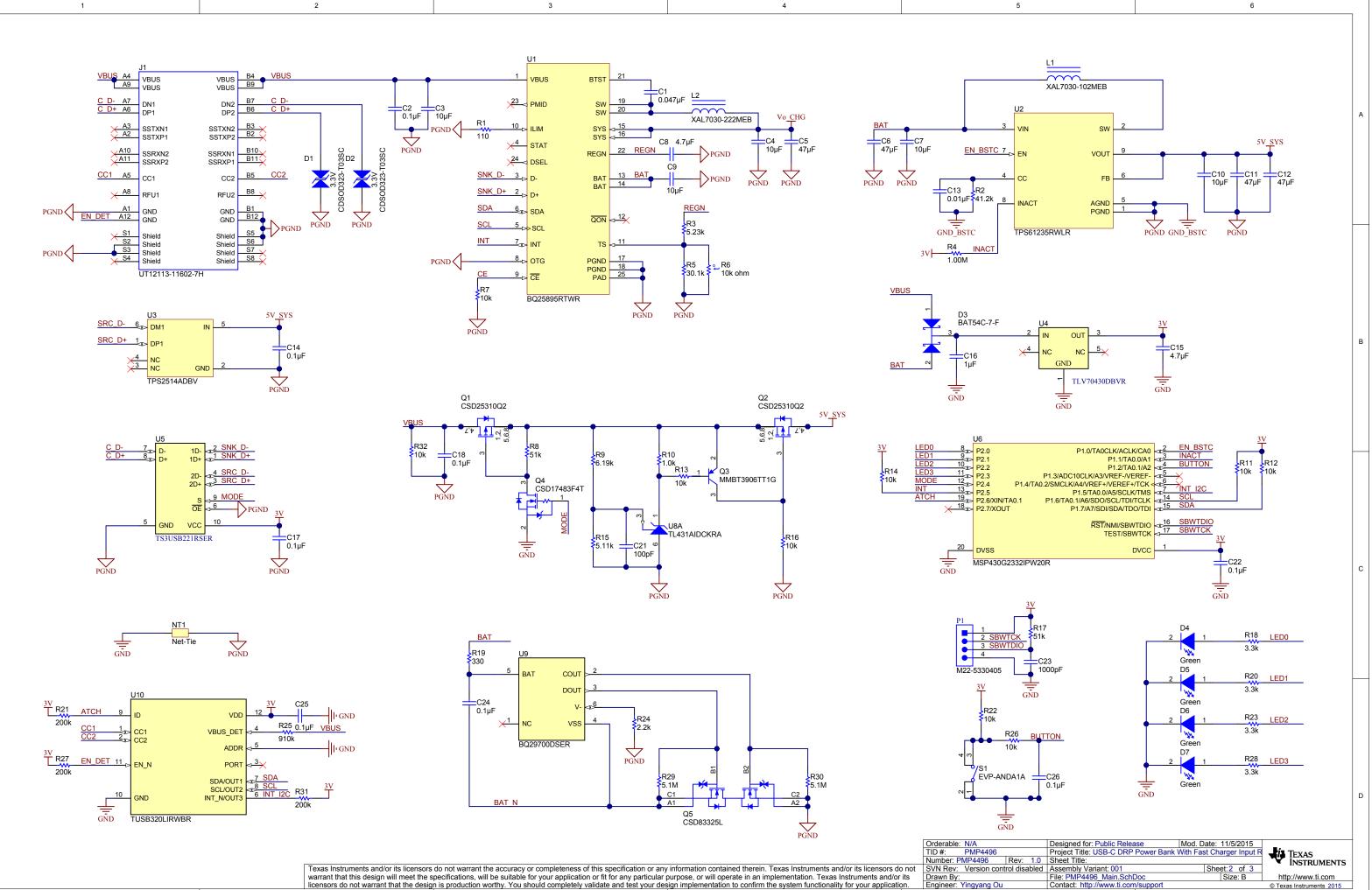
A		Revision 1.0	Notes For Public Release	
В	VBUS: 5-12V \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow			
D		:: 001	Mod. Date: 11/5/2015 k With Fast Charger Input R Size: B Size:	î S

Revision History				
Revision Notes				
1.0 For Public Release				





licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.



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PCB LOGO Pb-Free Symbol

Label Table				
Variant	Label Text			
001	ChangeMe!			
002	ChangeMe!			

А

в

С

D

ZZ1 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

1

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	se Mod. D	ate: 11/5/2015	_
TID #: PMP4496	Project Title: USB-C DRP F	Power Bank With Fas	st Charger Input R	TEXAS INSTRUMENTS
Number: PMP4496 Rev: 1.0	Sheet Title:			INSTRUMENTS
SVN Rev: Version control disabled	Assembly Variant: 001		Sheet: 3 of 3	in official trib
Drawn By:	File: PMP4496_Hardware.S	SchDoc	Size: B	http://www.ti.com
Engineer: Yingyang Ou Contact: http://www.ti.com/support			© Texas Instruments 2015	
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licensors do not warrant that the desig	n is production worthy. You should completely validate an	st your design implementation to confirm the system func	tionality for your application.	Enginee
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